

ABSTRACT

An adhesive film used for bonding a semiconductor component or a liquid crystal display component with a substrate, the adhesive film being composed of a resin composition containing a curable resin and a filler, and the adhesive film showing a water vapor transmission rate of 30 [g/m²·24h] or above, wherein the curable resin preferably contains photo-curable resin, thermosetting resin, or curable resin cured both by light and heat. The filler preferably contains a porous filler, the filler preferably has a mean void diameter of 0.1 to 5 nm, and the adhesive film preferably shows a water vapor transmission rate at 25°C of 4 [g/m²·24h] or above.